

L Number	Hits	Search Text	DB	Time stamp
1	11	((test or testing or tested) with electrical with (poor and good)) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 10:30
17	593	"PEELING LAYER"	USPAT; US-PGPUB	2003/02/21 12:21
18	8906	flip-chip or "flip chip"	USPAT; US-PGPUB	2003/02/21 14:51
19	519609	bond or bonding or bonded	USPAT; US-PGPUB	2003/02/21 14:51
20	642783	@ad>19990114 or @rlad>19990114	USPAT; US-PGPUB	2003/02/21 12:22
21	6	"PEELING LAYER" AND (flip-chip or "flip chip") AND (bond or bonding or bonded)	USPAT; US-PGPUB	2003/02/21 12:22
22	1	("PEELING LAYER" AND (flip-chip or "flip chip") AND (bond or bonding or bonded)) NOT (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 12:25
23	7	"PEELING LAYER" AND (flip-chip or "flip chip")	USPAT; US-PGPUB	2003/02/21 12:25
24	2	("PEELING LAYER" AND (flip-chip or "flip chip")) NOT (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 12:28
25	39589	(test or testing or tested) and (peeling or peel or peeled)	USPAT; US-PGPUB	2003/02/21 14:51
26	330	(flip-chip or "flip chip") and ((test or testing or tested) and (peeling or peel or peeled))	USPAT; US-PGPUB	2003/02/21 12:29
27	151	((flip-chip or "flip chip") and ((test or testing or tested) and (peeling or peel or peeled))) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:27
28	2281	adhesive with "thermoplastic resin"	USPAT; US-PGPUB	2003/02/21 13:32
29	1749	(adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:27
30	34	(flip-chip or "flip chip") and ((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 13:28
31	1649	adhesive with "thermosetting resin"	USPAT; US-PGPUB	2003/02/21 13:34
32	245	((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)) and (adhesive with "thermosetting resin")	USPAT; US-PGPUB	2003/02/21 13:32
33	12	(flip-chip or "flip chip") and (((adhesive with "thermoplastic resin") not (@ad>19990114 or @rlad>19990114)) and (adhesive with "thermosetting resin"))	USPAT; US-PGPUB	2003/02/21 13:32
34	51	adhesive with "low melting point metal"	USPAT; US-PGPUB	2003/02/21 13:36
35	34	(adhesive with "low melting point metal") not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:36
36	8	(flip-chip or "flip chip") and ((adhesive with "low melting point metal") not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 13:40
37	15	"torsional force" with adhesive	USPAT; US-PGPUB	2003/02/21 13:40
38	774960	test or testing or tested	USPAT; US-PGPUB	2003/02/21 13:40
39	8	("torsional force" with adhesive) and (test or testing or tested)	USPAT; US-PGPUB	2003/02/21 13:40
40	6	((("torsional force" with adhesive) and (test or testing or tested)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/21 13:41
41	12	("torsional force" with adhesive) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:41
42	6	((("torsional force" with adhesive) not (@ad>19990114 or @rlad>19990114)) not (((("torsional force" with adhesive) and (test or testing or tested)) not (@ad>19990114 or @rlad>19990114)))	USPAT; US-PGPUB	2003/02/21 13:42
43	197	torsional with adhesive	USPAT; US-PGPUB	2003/02/21 13:42
44	167	(torsional with adhesive) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/21 13:43
45	391738	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2003/02/21 13:43

-	28146	(test or testing or tested) with electrical	USPAT; US-PGPUB	2003/02/20 13:01
-	204	438/17.ccls. and ((test or testing or tested) with electrical)	USPAT; US-PGPUB	2003/02/20 12:43
-	126	(438/17.ccls. and ((test or testing or tested) with electrical)) not (@ad>19990114 or @rlad>19990114)	USPAT; US-PGPUB	2003/02/20 12:43
-	16	(flip-chip or "flip chip") and ((438/17.ccls. and ((test or testing or tested) with electrical)) not (@ad>19990114 or @rlad>19990114))	USPAT; US-PGPUB	2003/02/20 13:00
-	17	(test or testing or tested) with electrical with (poor and good)	USPAT; US-PGPUB	2003/02/20 13:02